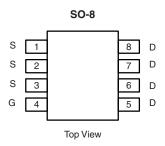




# N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
30	0.0094 at V <sub>GS</sub> = 10 V	16	14 nC		
	0.0115 at V <sub>GS</sub> = 4.5 V	14	14110		



Ordering Information: Si4684DY-T1-E3 (Lead (Pb)-free)

Si4684DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

## **FEATURES**

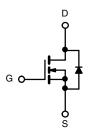
- Halogen-free According to IEC 61249-2-21 Definition
- Extremely Low Q<sub>gd</sub> for Low Switching Losses
- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

## **APPLICATIONS**

- High-Side DC/DC Conversion
  - Notebook
  - Server



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b>	<b>S</b> (T <sub>A</sub> = 25 °C, unle	ss otherwise no	ted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V		
Gate-Source Voltage	V <sub>GS</sub>	± 12			
	T <sub>C</sub> = 25 °C		16		
Continuous Dusin Commant (T., 150 °C)	T <sub>C</sub> = 70 °C		12.9		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	12 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		9.5 <sup>b, c</sup>	_ ,	
Pulsed Drain Current		I <sub>DM</sub>	50	A	
Continuous Courses Brain Binds Coursest	T <sub>C</sub> = 25 °C		4.0		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.3 <sup>b, c</sup>	7	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	20		
Avalanche Energy		E <sub>AS</sub>	20	mJ	
	T <sub>C</sub> = 25 °C		4.45		
Maximum Davian Dissipation	T <sub>C</sub> = 70 °C	_	2.85	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.50 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		1.6 <sup>b, c</sup>		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	36	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>th IF</sub>	22	28		

## Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 90  $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	T\m	Max.	Unit	
Static	Symbol	lest Conditions	WIIN.	Тур.	wax.	Unit	
	V	V 0VI 050 ·· A	20			V	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	30	20		V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		30		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	)/		4.5	4 -		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	0.6	4.4	1.5	V	
0-1- 0	. ` ′	$V_{DS} = V_{GS}$ , $I_D = 5 \text{ mA}$		1.1	400	A	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 16 \text{ A}$		0.0078	0.0094	Ω	
	DO(OH)	$V_{GS} = 4.5 \text{ V}, I_D = 9.5 \text{ A}$		0.0092	0.0115		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 16 A		45		S	
Dynamic <sup>b</sup>	ı			1	ı		
Input Capacitance	C <sub>iss</sub>			2080			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		340		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			135			
Total Gate Charge	$Q_{g}$	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 11 \text{ A}$		30	45	nC	
	$\mathbf{Q}_{g}$			14	21		
Gate-Source Charge	Q <sub>gs</sub> Q <sub>gd</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 11 \text{ A}$		3			
Gate-Drain Charge				2.8			
Gate Resistance	$R_g$	f = 1 MHz	0.2	0.55	0.9	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			15	25		
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.87 \Omega$		60	100		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		28	45		
Fall Time	t <sub>f</sub>			9	15	no	
Turn-On Delay Time	t <sub>d(on)</sub>			12	20	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 1.87 $\Omega$ $I_D \cong$ 8 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		12	20		
Turn-Off Delay Time	t <sub>d(off)</sub>			45	70		
Fall Time	t <sub>f</sub>			11	18		
<b>Drain-Source Body Diode Characterist</b>	ics						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			4	Α.	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	-			50	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 2.3 A		0.70	1.1	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	-		30	45	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			26	40	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 9.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		16		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			14			

### Notes

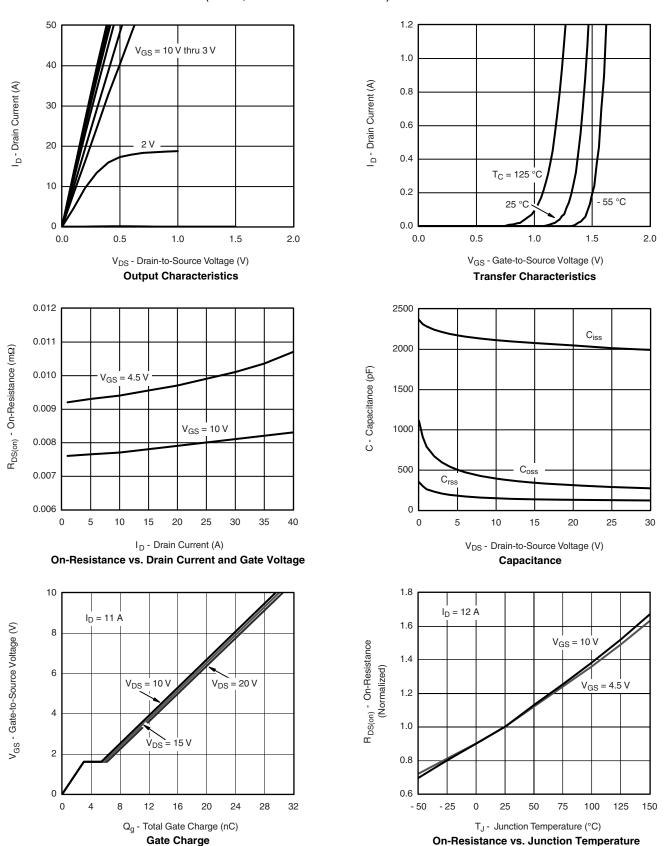
- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



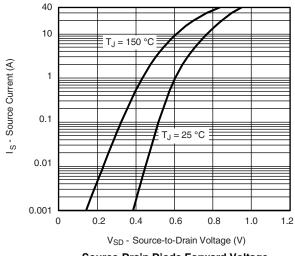


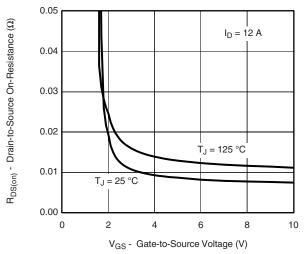
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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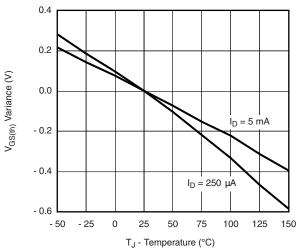
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

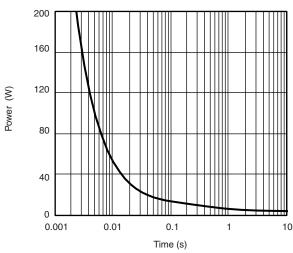




Source-Drain Diode Forward Voltage

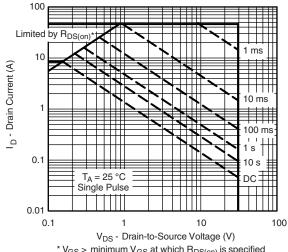






**Threshold Voltage** 

Single Pulse Power, Junction-to-Ambient



\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

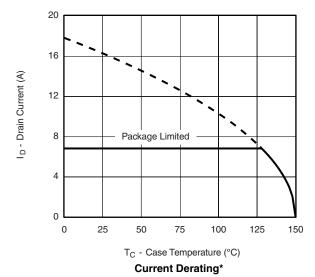
Safe Operating Area, Junction-to-Ambient

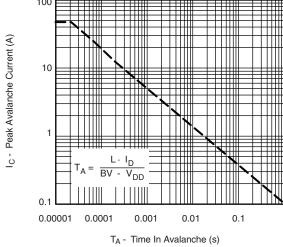






## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





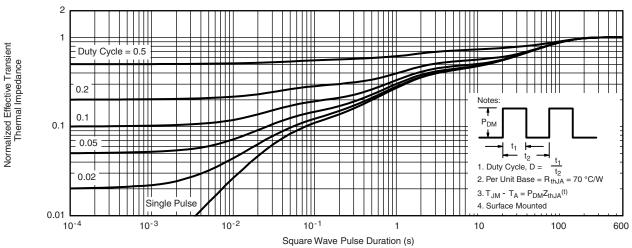
Single Pulse Avalanche Capability

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

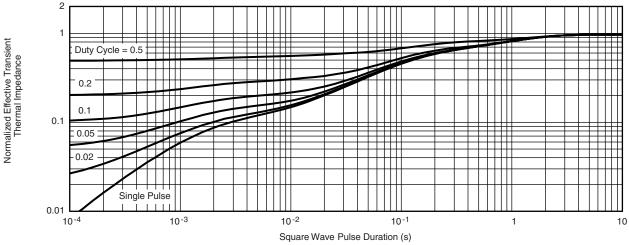
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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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